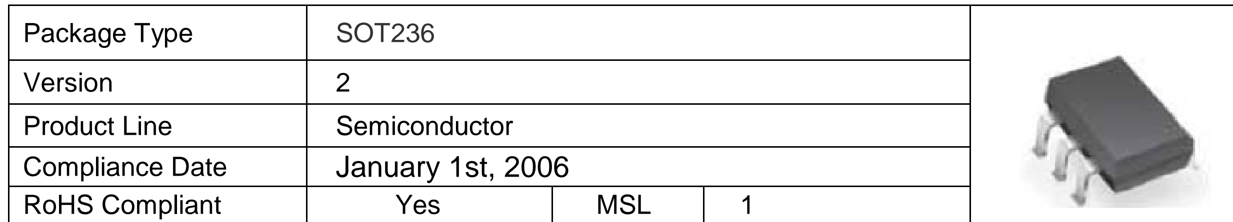
MATERIAL DECLARATION SHEET



Package Type	SOT236		
Version	2		
Product Line	Semiconductor		
Compliance Date	January 1st, 2006		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material Weight (g)	Homogeneous Material/ Substances	CASRN if applicable	Material Mass (%)	Material Mass (%) of total units wt.	Subpart Mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.00854	Fused Silica (SiO_2)	60676-86-0	87.70	45.23	51.58
				Epoxy Resin	Trade secret	5.00	2.58	
				Phenol Resin	Trade secret	5.00	2.58	
				Epoxy, Cresol Novolac	29690-82-2	2.00	1.03	
				Carbon Black	1333-86-4	0.30	0.15	
2	Leadframe	Copper Alloy	0.00674	Copper (Cu)	7440-50-8	94.95	38.67	40.73
				Iron (Fe)	7439-89-6	2.35	0.96	
				Silver (Ag)	7440-22-4	2.50	1.02	
				Zinc (Zn)	7440-66-6	0.12	0.05	
				Phosphorus (P)	7723-14-0	0.08	0.03	
3	Chip	Silicon	0.00043	Silicon (Si)	7440-21-3	97.40	2.51	2.58
				Aluminum (Al)	7429-90-5	1.27	0.03	
				Nickel (Ni)	7440-02-0	1.28	0.03	
				Gold (Au)	7440-57-5	0.06	0.00	
4	Die Attach	Epoxy	0.00004	Silver (Ag)	7440-22-4	88.50	0.22	0.25
				Formaldehyde, polymer with aniline, maleated, cyclized	67784-74-1	5.50	0.01	
				Epoxy	25036-25-3	5.50	0.01	
				Epoxy	25068-38-6	0.50	0.00	
5	Bond wires	Gold	0.00007	Gold (Au)	7440-57-5	100.00	0.45	0.45
6	Terminal Finish	Tin	0.00073	Tin (Sn)	07440-31-5	100.00	4.41	4.41
		Total weight (g)	0.01655					

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society